

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Kiyoshi Arita
Serial No.: TBD
Filing Date: Herewith
Title: METHOD OF MANUFACTURING SEMICONDUCTOR DEVICE AND
CUTTING APPARATUS FOR CUTTING SEMICONDUCTOR WAFER
Docket No.: 36395

INFORMATION DISCLOSURE STATEMENT

Mail Stop PATENT APPLICATION
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

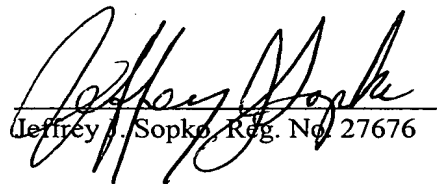
Sir:

In accordance with Rule 56, applicant is aware of the publications listed in the enclosed copy of Patent Office Form 1449. A copy of each of the publications is enclosed herewith.

Respectfully submitted,

PEARNE & GORDON LLP

By:


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Form PTO-1449	U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE	ATTY. DOCKET NO. 36395	SERIAL NO. TBD
INFORMATION DISCLOSURE CITATION BY APPLICANT (USE SEVERAL SHEETS IF NECESSARY) Page 1 of 1		APPLICANT: Kiyoshi Arita	
		FILING DATE: Herewith	GROUP ART UNIT: TBD

U.S. PATENT DOCUMENTS							
Examiner Initial		Document No.	Date	Name	Class	Subclass	Filing Date
	A						
	B						
	C						
	D						
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	F						
	G						
	H						
	I						
	J						
	K						
	L						

FOREIGN PATENT DOCUMENTS							
		Document No.	Date	Country	Class	Subclass	Translation
	M	2002-93752	3/2002	JP			Cited in Spec. (pg. 2)
	N						
	P						
	Q						

OTHER REFERENCES (Including Author, Title, Date, Pertinent Pages, Etc.)		
	R	
	S	
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Examiner:	Date Considered
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*Examiner: Initial if reference considered, regardless of whether citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.